

PATENT ABSTRACTS OF JAPAN

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(21)Application number : **2000-331617** (71)Applicant : **KYOCERA CORP**

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(54) WIRING BOARD

(57)Abstract:

PROBLEM TO BE SOLVED: To solve the problem that intervals in a through hole cannot be set to 300 μm or less since migration due to a metal ion is generated between feed-through conductors.

SOLUTION: This wiring board 6 has a plurality of insulating layers 1a to 1d where an organic resin is dipped into a glass fiber base A, a circuit conductor layer 2 provided on the surface of the insulating layers 1a to 1d and between the layers, a resin layer 5 that is formed on the internal wall of the through hole 3 punched in the insulating layers 1a to 1d and covers the end section of the glass fiber base A exposed onto the internal wall, and the feed- through conductor 4 that is filled into the inside of the through hole 3 and electrically connects the circuit conductor layers 2 positioned above and below. In the resin layer 5, the maximum thickness should be provided in

a region of $\pm 40\%$ in a depth wise direction with a site having $1/2$ the depth of the through hole 3 as a center. The migration of the metal ion between the feed- through conductors 4 is prevented effectively, thus preventing the generation of ion migration

